

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	153	goto-toshio.in.	US-PGPUB; USPAT	OR	OFF	2008/11/07 15:13
L2	1	L1 and (plasma same liquid same flatten\$3)	US-PGPUB; USPAT	OR	OFF	2008/11/07 15:13
L3	8856	(etch\$3 near back or flatten\$3) same plasma	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/07 15:14
L4	97	L3 and (supply\$3 near (liquid or water))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/07 15:14
L5	22	4 and bias\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/07 15:15
L6	11	5 and @pd< "20030324"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/07 15:15
L7	2	("2001237212").FN.	JPO; DERWENT	OR	OFF	2008/11/07 15:53
L8	7	(atmospheric near pressure near plasma) same (bias\$3 same (substrate or wafer))	US-PGPUB; USPAT	OR	OFF	2008/11/07 16:08
L9	58	(atmospheric near pressure near plasma) same (bias\$3 with "DC" or "AC")	US-PGPUB; USPAT	OR	OFF	2008/11/07 16:12
L10	17	9 and @pd< "20030324"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/07 16:12
L11	9	10 and ((surface with polish\$3) or flatten\$3 or etch\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/07 16:13

L12	3	(atmospheric near pressure near plasma) same (bias\$3 with ("DC" or "AC"))	US-PGPUB; USPAT	OR	OFF	2008/11/07 16:15
L13	10	10 and (surface with (polish\$3 or flatten\$3 or etch\$3 or treat\$3 or modificat\$3 or irradiat\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/07 16:21
L14	3	(atmospheric near pressure near plasma) same (bias\$3 with ("DC" or "AC"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/07 16:27
L15	5	(plasma near (polish\$3 or flatten\$3)) same bias\$3	US-PGPUB; USPAT	OR	OFF	2008/11/07 16:55
L16	0	(atmospheric near pressure near plasma) same (bias\$3 same (substrate or wafer))	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/07 16:57
L17	0	(atmospheric near pressure near plasma) same (bias\$3 with ("AC" or "DC"))	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/07 16:58
L18	612	plasma same (bias\$3 with ("AC" or "DC"))	EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/07 16:59
L19	479	18 and @pd< "20030324"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/07 16:59
L20	57	19 and (polish\$3 or flatten\$3 or modificat\$3 or treat\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/07 17:00
L21	2	20 and (pressure same "ATM")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/07 17:16
L22	0	20 and (pressure with atmospher)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/07 17:17

L23	17	20 and pressure	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/07 17:17
L24	17	9 and @pd<"20030324"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/07 17:23
L25	70	(atmospheric near pressure near plasma) and (bias\$3 same (substrate or wafer))	US-PGPUB; USPAT	OR	OFF	2008/11/07 17:26
L26	16	25 and @pd<"20030324"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/11/07 17:26

11/7/08 5:50:33 PM

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